

ABSTRACT OF THE DISCLOSURE

Light emitting diode (LED) packages are made by first providing a platelike frame having a plurality of cells, each of which is composed of a main plate and a separate arm. Secondly, an LED die and a reflecting ring are respectively mounted on top of each main plate such that the die is located at a center of the reflecting ring. Then a conductive wire is connected between the top surface of the die and a top surface of the separate arm by wire bonding. A domed transparent encapsulant is then molded on each of the cells. The encapsulant encapsulates the die, the reflecting ring and the conductive wire and covers the main plate and the separate arm, and fills a space between the main plate and the separate arm to remain their spaced apart. Finally, the frame is cut according to the size of each cell to obtain the LED packages.